

CLAIMS

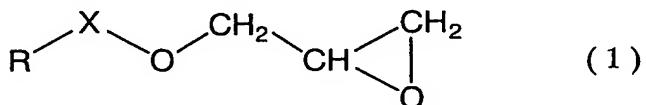
1. A thermosetting resin composition comprising component (A) and component (B) below, wherein the sum of the content of the component (A) and component (B) is 90% by weight or more based on the composition;

component (A): at least one selected from amino acids and imidazoles, and

component (B): an epoxy group-containing ethylene copolymer obtained by polymerizing monomer (b₁) and monomer (b₂) below:

monomer (b₁): at least one selected from ethylene and propylene, and

monomer (b_2): a monomer represented by formula (1) below:



(wherein R represents a hydrocarbon group of a carbon number of from 2 to 18 having a double bond, at least one of hydrogen atoms of the hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group.)

2. The thermosetting resin composition according to claim 1, wherein the content of a structural unit derived from monomer (b₂) is 1 to 30 parts by weight relative to 100 parts by weight of component (B).

3. The thermosetting resin composition according to

claim 1, wherein the content of a structural unit derived from monomer (b₁) is 30 to 75 parts by weight relative to 100 parts by weight of component (B).

4. The thermosetting resin composition according to
5 claim 1, wherein component (B) is a copolymer obtained by polymerizing monomer (b₁), monomer (b₂) and monomer (b₃) below:

monomer (b₃): a monomer which has a functional group copolymerizable with ethylene, does not have a functional group reactive with an epoxy group, and is different from either of
10 monomer (b₁) and monomer (b₂).

5. The thermosetting resin composition according to
claim 1, wherein the ratio by weight of component (A) and component (B) ((A)/(B)) is from 0.1/99.9 to 10/90.

6. The thermosetting resin composition according to
15 claim 1, which further contains component (C) below:

component (C): an antioxidant.

7. The thermosetting resin composition according to
claim 6, wherein component (C) is at least one selected from
the group consisting of a phenolic antioxidant, a phosphoric
20 antioxidant and a sulfuric antioxidant.

8. The thermosetting resin composition according to
claim 1, wherein component (A) is an amino acid, and the amino
acid is at least one selected from aminoacetic acid, β -alanine,
4-aminobutyric acid, aminovaleric acid, 6-aminohexanoic
25 acid, 11-aminoundecanoic acid and 12-aminododecanoic acid.

9. The thermosetting resin composition according to claim 1, wherein component (A) is an imidazole, and the imidazole is at least one selected from

1-cyanoethyl-2-ethyl-4-methylimidazolium trimellitate,

5 1-cyanoethyl-2-undecylimidazolium trimellitate,

1-cyanoethyl-2-phenylimidazolium trimellitate,

2,4-diamino-6-[2'-methylimidazolyl-(1')]-ethyl-s-triazine,

2,4-diamino-6-(2'-undecylimidazolyl)-ethyl-s-triazine,

10 2,4-diamino-6-[2'-ethyl-4-methylimidazolyl-(1')]-ethyl-s-triazine, an adduct of

2,4-diamino-6-[2'-methylimidazolyl-(1')]-ethyl-s-triazine

with isocyanuric acid, an adduct of 2-phenylimidazole with isocyanuric acid, and an adduct of 2-methylimidazole with

15 isocyanuric acid.

10. An adhesive film comprising the thermosetting resin composition according to claim 1.

11. The adhesive film according to claim 10, which is obtained by extrusion-molding the thermosetting resin

20 composition according to claim 1.

12. An adhesive film, which is obtainable by further irradiating an electron beam on the adhesive film according to claim 10.

13. The adhesive film according to claim 12, which is obtainable by performing the electron beam irradiation plural

times.

14. A laminate, which is obtainable by laminating the adhesive film according to claim 10 or 12 with an adherent, and thermally curing the resultant.